

Amendments to the Claims:

If entered, this listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) An integrated circuit device comprising:
 - an integrated circuit die fixably attached to a substrate and electrically connected to a metal trace on said substrate;
 - an encapsulating layer overlying said integrated circuit die
 - 5 and substrate; and
 - an antenna structure of conductive loaded resin based material
- ~~comprising micron conductive fiber in a resin host~~ overlying said encapsulating layer and directly contacting said metal trace through an opening in said encapsulating layer wherein said conductive loaded resin based material

10 comprises micron conductive fiber in a resin-based material and wherein said micron conductive fiber has a diameter of between 3 μm and about 12 μm and a length of between 2 mm and about 14 mm.
2. (Previously Presented) The device according to Claim 1 wherein the ratio, by weight, of said micron conductive fiber to said resin host is between about 0.20 and about 0.40.

3. (Currently Amended) The device according to Claim 1 wherein said conductive loaded resin-based material further comprises ~~further comprising~~ micron metal powder.

4. (Original) The device according to Claim 3 wherein said metal powder is nickel, copper, or silver.

5. (Original) The device according to Claim 3 wherein said metal powder is a non-conductive material with a metal plating.

6. (Original) The device according to Claim 5 wherein said metal plating is nickel, copper, silver, or alloys thereof.

7. (Original) The device according to Claim 3 wherein said metal powder comprises a diameter of between about 3 μm and about 12 μm .

8. (Currently Amended) The device according to Claim wherein said conductive loaded resin-based material further comprises ~~further comprising~~ micron non-metal powder.

9. (Original) The device according to Claim 8 wherein said non-metal powder is carbon, graphite, or an amine-based material.

10. (Previously Presented) The device according to Claim 1 further comprising a combination of metal powder and non-metal powder.

11. (Canceled)

12. (Currently Amended) The device according to Claim 1 wherein said micron conductive fiber is nickel plated carbon fiber, stainless steel fiber, copper fiber, silver fiber or combinations thereof.

13. (Canceled)

14. (Canceled)

15. (Canceled)

16. (Canceled)

17. (Canceled)

18. (Previously Presented) The device according to Claim 1 wherein said encapsulating layer comprises a resin-based material.

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19. (Canceled)

20-72. (Canceled)